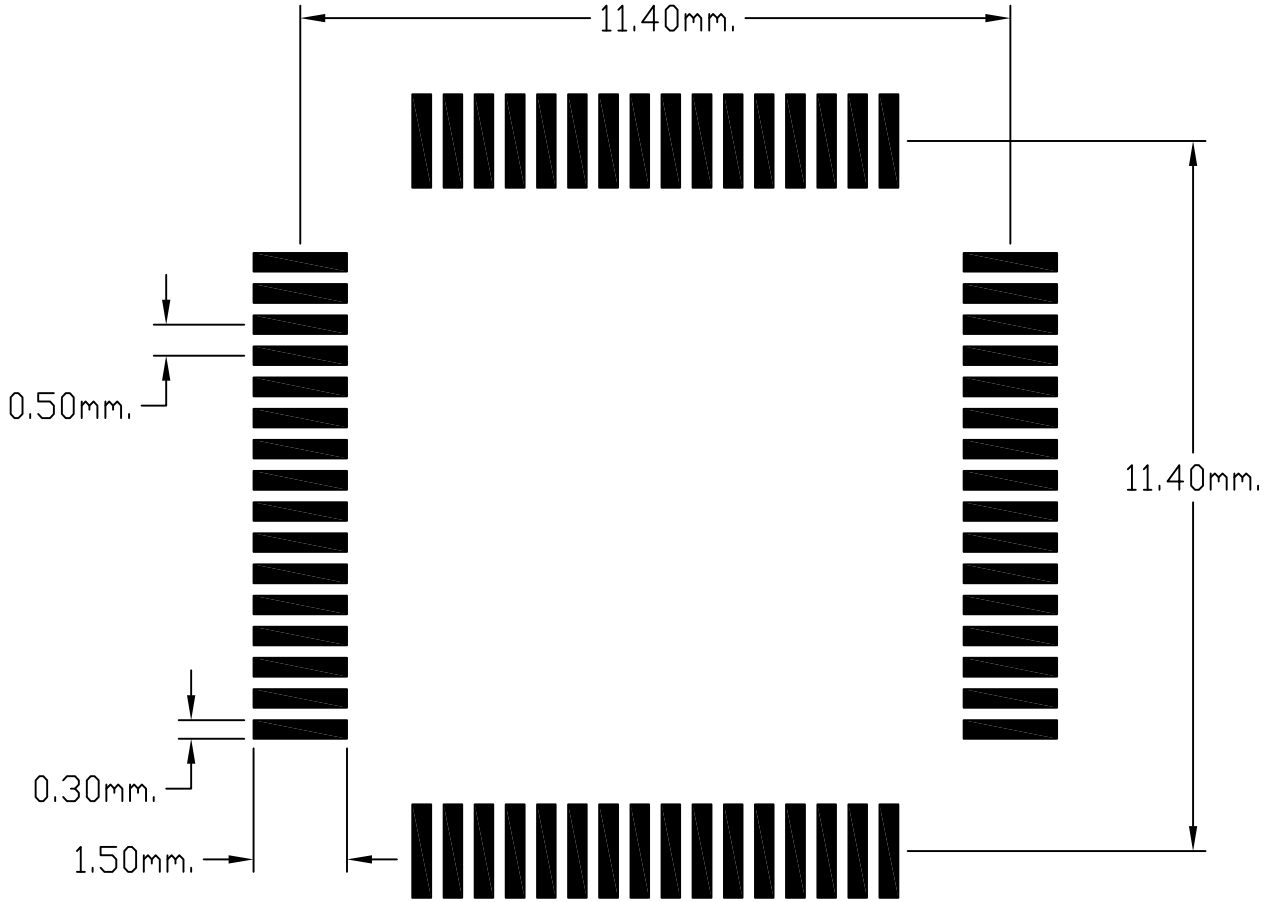

PKG. CODES
[C64E-4R / C64E+4R]
[C64E-9R / C64E+9R]
[C64E-13R / C64E+13R]

NOTES:

1. THERMAL EXPOSED PAD ON TOP SIDE OF PACKAGE ONLY
2. PACKAGE IS REVERSE CAVITY PADDLE
3. REFERENCE PKG. OUTLINE: 21-0162
4. LAND PATTERN COMPLIES TO: IPC7351A.
5. TOLERANCE: +/- 0.02 MM.
6. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
7. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—

maxim integrated™

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.
This document is subject to change without notice.
Contact technical support at http://www.maxim-ic.com/support for further questions.

TITLE:
PACKAGE LAND PATTERN, [C64E] TQFP, THERMAL EXPOSED PAD ON TOP SIDE ONLY

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